# NJD35N04G, NJVNJD35N04G, NJVNJD35N04T4G

# NPN Darlington Power Transistor

This high voltage power Darlington has been specifically designed for inductive applications such as Electronic Ignition, Switching Regulators and Motor Control.

## **Features**

- Exceptional Safe Operating Area
- High V<sub>CE</sub>; High Current Gain
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices\*

## **Benefits**

- Reliable Performance at Higher Powers
- Designed for Inductive Loads
- Very Low Current Requirements

# **Applications**

- Internal Combustion Engine Ignition Control
- Switching Regulators
- Motor Controls
- Light Ballast
- Photo Flash

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Sustaining Voltage	V <sub>CEO</sub>	350	Vdc
Collector-Base Breakdown Voltage	V <sub>CBO</sub>	700	Vdc
Collector-Emitter Breakdown Voltage	V <sub>CES</sub>	700	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	5.0	Vdc
Collector Current Continuous Peak	I <sub>C</sub>	4.0 8.0	Adc
Base Current	I <sub>B</sub>	0.5	Adc
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	45 0.36	W W/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



# ON Semiconductor®

http://onsemi.com

DARLINGTON
POWER TRANSISTORS
4 AMPERES
350 VOLTS
45 WATTS



DPAK CASE 369C STYLE 1

#### **MARKING DIAGRAM**



Y = Year WW = Work Week NJD35N04 = Device Code G = Pb-Free Device

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NJD35N04G	DPAK (Pb-Free)	75 Units / Rail
NJVNJD35N04G	DPAK (Pb-Free)	75 Units / Rail
NJD35N04T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NJVNJD35N04T4G	DPAK (Pb-Free)	2,500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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# THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance Junction-to-Case Junction-to-Ambient	$egin{array}{c} {\sf R}_{ heta {\sf JC}} \ {\sf R}_{ heta {\sf JA}} \end{array}$	2.78 71.4	°C/W

# **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					L
Collector-Emitter Sustaining Voltage (I <sub>C</sub> = 10 mA, L = 10 mH)	V <sub>CEO(sus)</sub>	350	-	-	V
Collector Cutoff Current ( $V_{CE} = 500 \text{ V}$ ) ( $I_B = 0$ ) ( $V_{CE} = 500 \text{ V}$ , $T_C = 125^{\circ}\text{C}$ )	I <sub>CES</sub>	- -		50 250	μΑ
Collector Cutoff Current ( $V_{CE} = 250 \text{ V}$ ) ( $I_B = 0$ ) ( $V_{CE} = 200 \text{ V}$ , $T_C = 125^{\circ}\text{C}$ )	I <sub>CEO</sub>	- -	<u>-</u> -	50 250	μΑ
Emitter Cutoff Current (V <sub>BE</sub> = 5.0 Vdc)	I <sub>EBO</sub>	-	-	5.0	μΑ
ON CHARACTERISTICS	<b>'</b>			1	
Collector–Emitter Saturation Voltage ( $I_C$ = 2.0 A, $I_B$ = 20 mA) ( $I_C$ = 2.0 A, $I_B$ = 20 mA 125°C)	V <sub>CE(sat)</sub>	- -	- -	1.5 1.5	V
Base–Emitter Saturation Voltage ( $I_C$ = 2.0 A, $I_B$ = 20 mA) ( $I_C$ = 2.0 A, $I_B$ = 20 mA 125°C)	V <sub>BE(sat)</sub>	- -	- -	2.0 2.0	V
Base–Emitter On Voltage (I <sub>C</sub> = 2.0 A, V <sub>CE</sub> = 2.0 V) (I <sub>C</sub> = 2.0 A, V <sub>CE</sub> = 2.0 V∏ 25°C)	V <sub>BE(on)</sub>	- -	- -	2.0 2.0	V
DC Current Gain (I <sub>C</sub> = 2.0 A, V <sub>CE</sub> = 2.0 V) (I <sub>C</sub> = 4.0 A, V <sub>CE</sub> = 2.0 Vdc)	h <sub>FE</sub>	2000 300	_ _	_ _ _	-
DYNAMIC CHARACTERISTICS			!	!	<u> </u>
Current–Gain – Bandwidth Product (I <sub>C</sub> = 2.0 A, V <sub>CE</sub> = 10 V, f = 1.0 MHz)	f <sub>T</sub>	90	_	_	MHz
Output Capacitance (V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0, f = 0.1 MHz)	C <sub>ob</sub>	-	60	-	pF
SWITCHING CHARACTERISTICS	•		•	•	•
V <sub>CC</sub> = 12 V, V <sub>clamp</sub> = 250 V, L = 4 mH I <sub>C</sub> = 2 A, I <sub>B1</sub> = 20 mA, I <sub>B2</sub> = -20 mA	t <sub>s</sub>	- -	18 0.8	- -	μSec

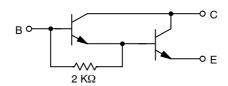


Figure 1. Darlington Circuit Schematic

# NJD35N04G, NJVNJD35N04G, NJVNJD35N04T4G

# TYPICAL CHARACTERISTICS

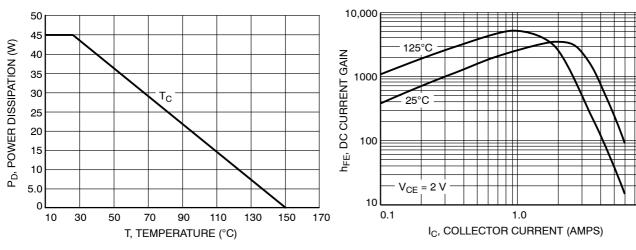


Figure 2. Power Derating

Figure 3. DC Current Gain

10

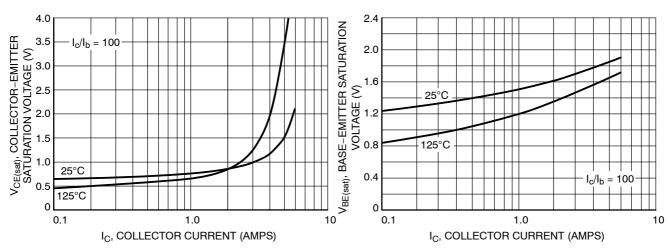


Figure 4. Collector-Emitter Saturation Voltage

Figure 5. Base-Emitter Saturation Voltage

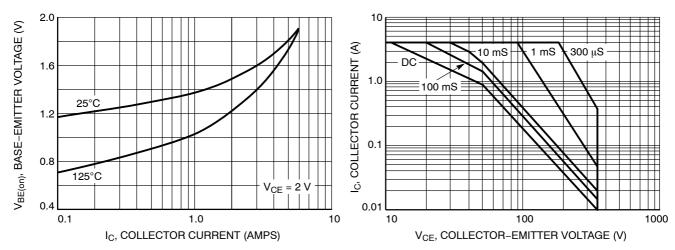
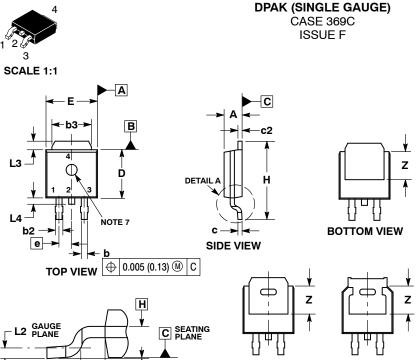
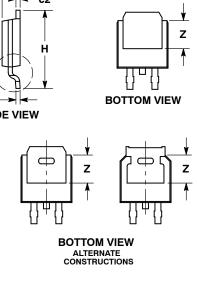


Figure 6. Base-Emitter Voltage

Figure 7. Forward Bias Safe Operating Area (FBSOA)







STYLE 5:

STYLE 4:

SITLE I.	STILE 2.	311	LE 3.	31	TLE 4.	STILE 5.
PIN 1. BASE	PIN 1. GA	ΓE PII	N 1. ANODE	F	PIN 1. CATHODE	PIN 1. GATE
<ol><li>COLLE</li></ol>	CTOR 2. DR	AIN	<ol><li>CATHOI</li></ol>	DE	<ol><li>ANODE</li></ol>	2. ANODE
<ol><li>EMITTE</li></ol>	R 3. SO	URCE	<ol><li>ANODE</li></ol>		<ol><li>GATE</li></ol>	<ol><li>CATHODE</li></ol>
<ol><li>COLLE</li></ol>	CTOR 4. DR	AIN	4. CATHO	DE	<ol><li>ANODE</li></ol>	4. ANODE
STYLE 6:	STYLE 7:	STYLE 8:		STYLE 9:		STYLE 10:
PIN 1. MT1	PIN 1. GATE	PIN 1. N/		PIN 1. A		PIN 1. CATHODE
2. MT2	<ol><li>COLLECTOR</li></ol>	2. CA	ATHODE	2. C	ATHODE	2. ANODE
<ol><li>GATE</li></ol>	<ol><li>EMITTER</li></ol>	3. AN	NODE	3. R	ESISTOR ADJUST	<ol><li>CATHODE</li></ol>
4. MT2	<ol> <li>COLLECTOR</li> </ol>	R 4. CA	ATHODE	4. C	ATHODE	4. ANODE

STYLE 3:

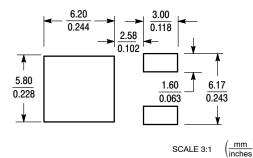
#### **SOLDERING FOOTPRINT\***

Α1

STYLE 2:

**DETAIL A** ROTATED 90° CW

STYLE 1:



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**DATE 21 JUL 2015** 

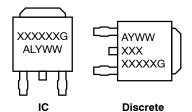
#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
  5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.

  6. DATUMS A AND B ARE DETERMINED AT DATUM
- 7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

# **GENERIC MARKING DIAGRAM\***



XXXXXX = Device Code = Assembly Location Α L = Wafer Lot Υ = Year

WW = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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